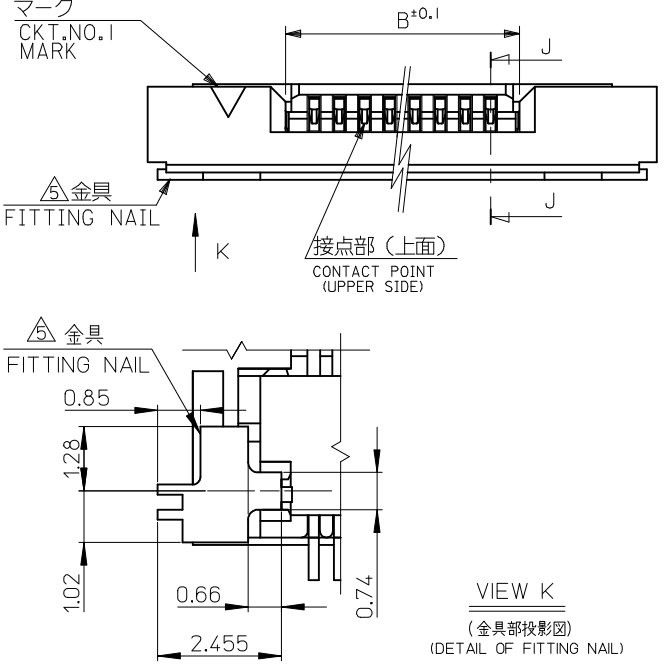
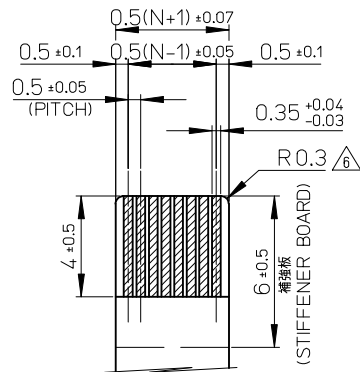


16.1	14.3	10.65	9.5	52745-2090	20
15.6	13.8	10.15	9	52745-1990	19
14.1	12.3	8.65	7.5	52745-1690	16
13.6	11.8	8.15	7	52745-1590	15
12.6	10.8	7.15	6	52745-1390	13
11.6	9.8	6.15	5	52745-1190	11
11.1	9.3	5.65	4.5	52745-1090	10
10.6	8.8	5.15	4	52745-0990	9
10.1	8.3	4.65	3.5	52745-0890	8
9.6	7.8	4.15	3	52745-0790	7
9.1	7.3	3.65	2.5	52745-0690	6
8.1	6.3	2.65	1.5	52745-0490	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

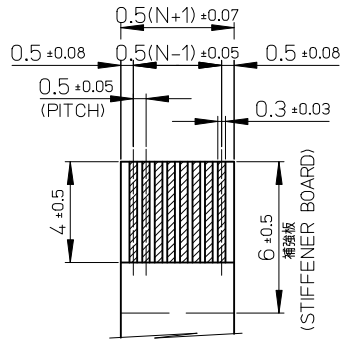


CONNECTOR SERIES NO. : 52745-**17

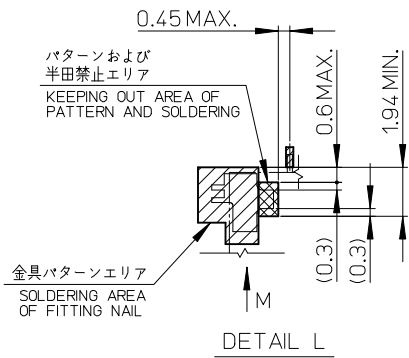
REVISED EC NO: J2016-0389 DRWN:IMORISHITA 2015/10/20 CHKD:KAKAHASHI 2015/10/20 APPR:YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER UNDER ±0.03	0.25 OVER 0.5 UNDER ±0.05	0.5 OVER 1.0 UNDER ±0.1	1.0 OVER 10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS
	DRAWN BY SAIHARA	DATE 1994/03/24	CHECKED BY SKUNISHI	DATE 2000/06/30	APPROVED BY KMORIKAWA	DATE 2010/07/16	MATERIAL NO.	SEE CHART
	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING		DOCUMENT NO. SD-52745-054		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



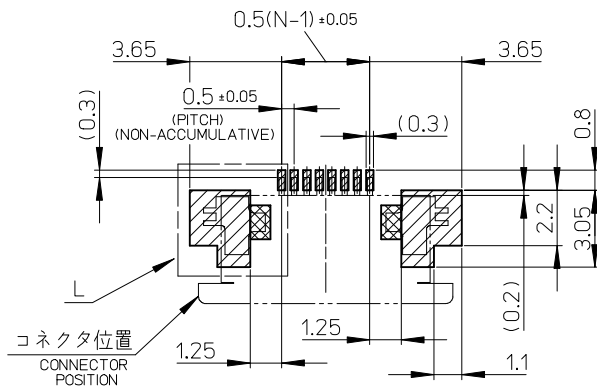
適合金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



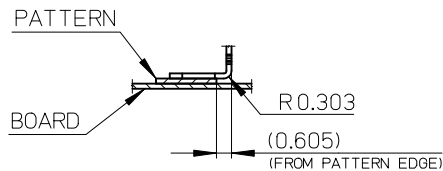
適合金めっきFFC推奨寸法
 APPLICABLE FFC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



DETAIL L



参考基板レイアウト
 (マウント面)
 RECOMMENDED P.C. BOARD
 PATTERN DIMENSION (REF.)
 (MOUNTING SIDE)



VIEW M
 (DETAIL OF FITTING NAIL
 ON PATTERN)

注記NOTES

1. 使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
 アクチュエータ: ホリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
 ターミナル: リン青銅、銅下地半田めっき (t=0.2)
 TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
 金具: リン青銅、銅下地半田めっき (t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART
 NO.52745-**17 SHOULD BE LOCKED.

3.

ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、
 基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM
 DATUM-H.
 UPPER DIRECTION: 0.1 MAXIMUM
 LOWER DIRECTION: 0.15 MAXIMUM

4.

偶数極に適用
 APPLY FOR EVEN CIRCUIT.

5.

ハターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6.

R0.3は、FPCの胴体部にかからないこと
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて:

打抜き方向は導体側から補強板を推奨致します。
 補強フィルム材質はポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
 RECOMMENDED MATERIAL:
 STIFFENER FILM: POLYIMIDE
 BONDING AGENT: THERMOSETTING BONDING AGENT

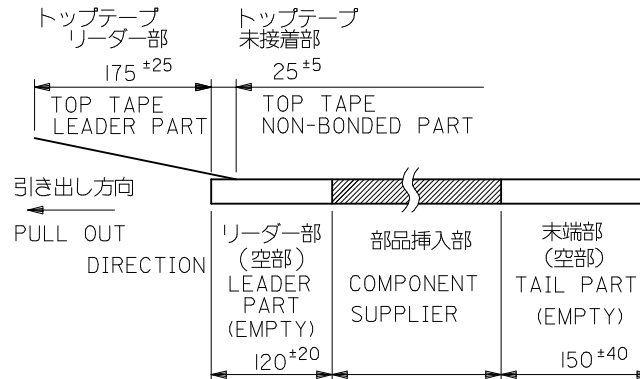
REVISED EC NO: J2016-0389 DRWN: MORISHITA 2015/10/20 CHKD: TAKAHASHI 2015/10/20 APPR: YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER UNDER ±0.03	0.25 OVER 0.5 UNDER ±0.05	0.5 OVER 1.0 UNDER ±0.1	1.0 OVER 10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±3 °
	DRAWN BY SAIHARA		DATE 1994/03/24		TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING		DRAWN BY SKUNISHI
CHECKED BY SKUNISHI		DATE 2000/06/30		APPROVED BY KMORIKAWA		DATE 2010/07/16	
MATERIAL NO. SEE SHEET 1				DOCUMENT NO. SD-52745-054		SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

注記 NOTES

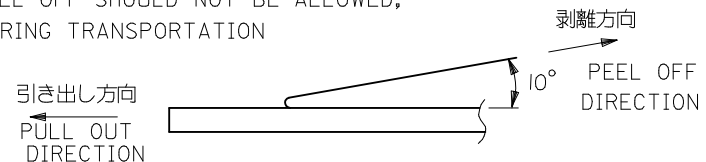
1. 製品番号 52745-**17 の梱包状態はアクチュエータがロックした状態とする。
 詳細寸法については図面 SD-52745-054 を参照下さい。
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-**17 SHOULD BE LOCKED
 RE DETAILED DIMENSIONS,SEE SD-52745-054

2. 梱包数量：1000個/リール
 NUMBER OF CONNECTORS:1000PCS/REEL

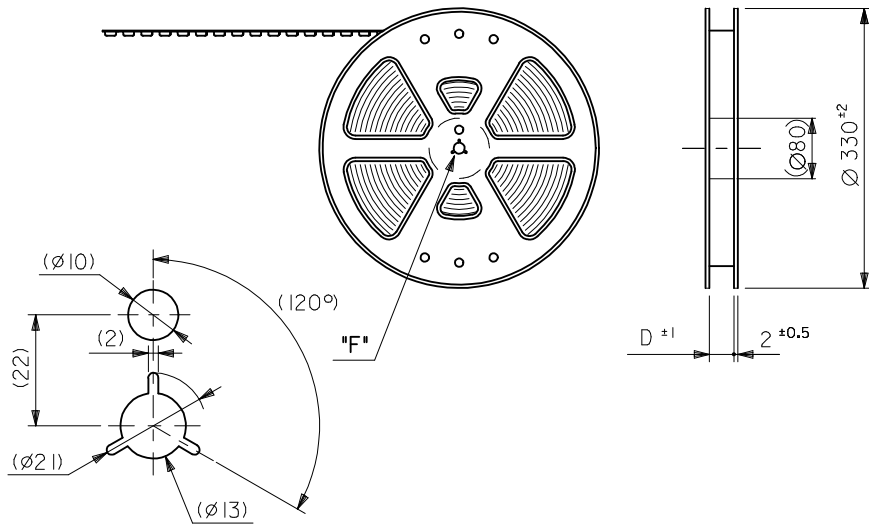
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)
 0.1N~0.7N(10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)
 PEELING OFF FORCE OF TOP TAPE
 0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION



引き出し方向
 PULL OUT
 DIRECTION

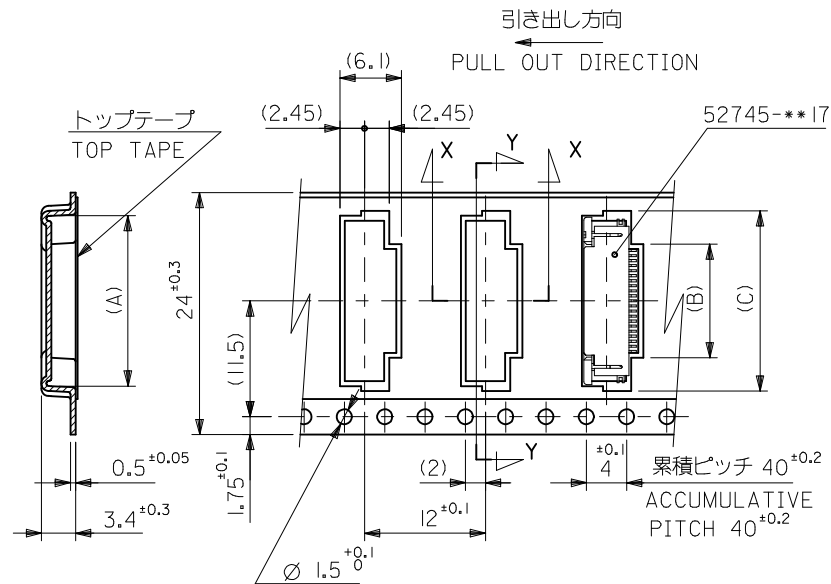


DETAIL "F"

5. 材料 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS) <リサイクル材を含む>

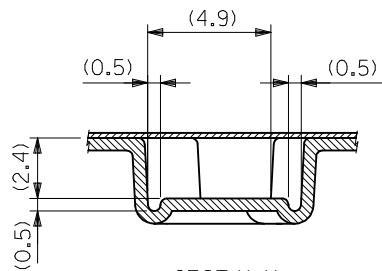
MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYREN(PS)
 <RECYCLE MATERIAL CONTAINED>

REVISED EC NO: J2016-0389 DRWN:IMORISHITA 2015/10/20 CHKD:KTAKAHASHI 2015/10/20 APPR:YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	MTAKAHASHI	04 2013/07/30	0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (1/3)		
	0.5 OVER	1.0 UNDER	±0.1	KTAKAHASHI	2013/07/30	molex		
1.0 OVER	10 UNDER	±---	APPROVED BY	DATE	DOCUMENT NO.			
10 OVER	30 UNDER	±---	YNOGAWA	2013/11/07	SD-52745-057			
30 OVER		±---	MATERIAL NO.		SHEET NO.			
ANGULAR	±---	°	SEE SHEET 1		1 OF 3			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



SECT.Y-Y

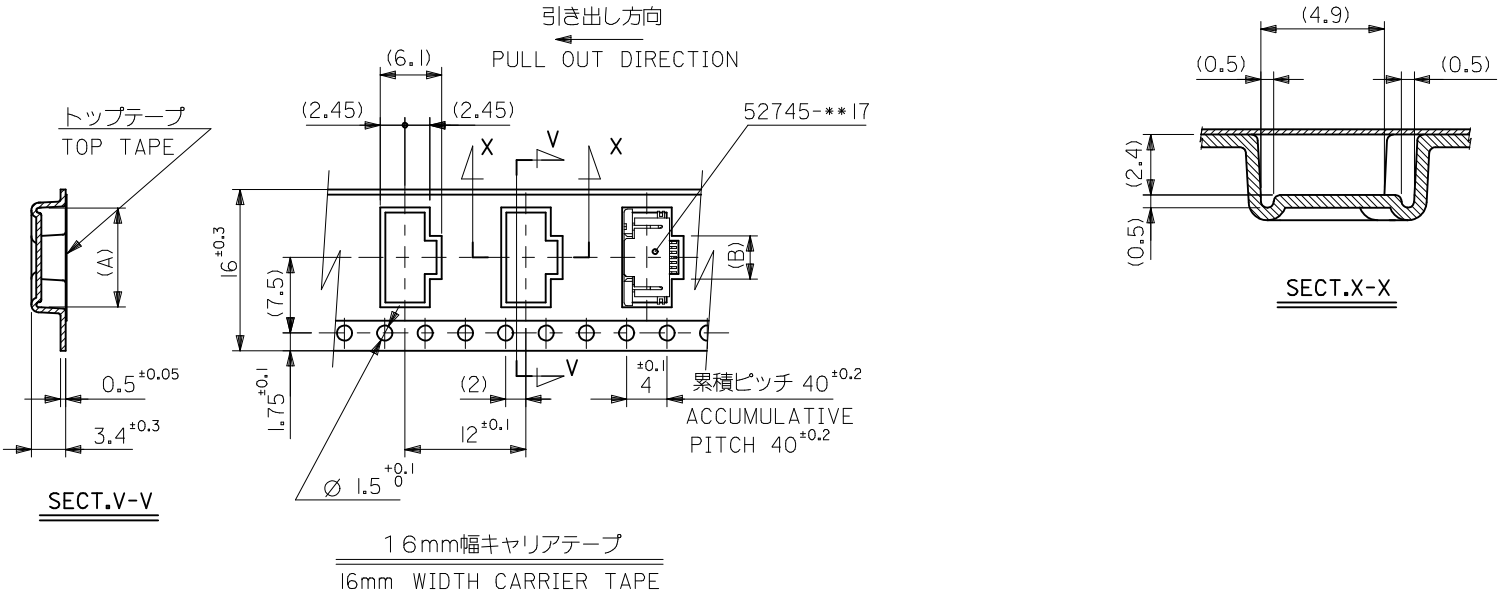
24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



SECT.X-X

24	25.5	17.4	10.8	16.4	52745-2090	20
		16.9	10.3	15.9	-1990	19
		15.4	8.8	14.4	-1690	16
		14.9	8.3	13.9	-1590	15
		13.9	7.3	12.9	-1390	13
		12.9	6.3	11.9	-1190	11
		12.4	5.8	11.4	-1090	10
		11.9	5.3	10.9	-0990	9
		11.4	4.8	10.4	-0890	8
		10.9	4.3	9.9	-0790	7
10.4	3.8	9.4	52745-0690	6		
キャリアテープ幅 CARRIER TAPE IDTH	D	(C)	(B)	(A)	ENG. NO.	極数 CIRCUIT

REVISED EC NO: J2016-0389 DRWN: MORISHITA 2015/10/20 CHKD: TAKAHASHI 2015/10/20 APPR: YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	MTAKAHASHI	104 2013/07/30	0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (2/3)		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex DOCUMENT NO. SD-52745-057 SHEET NO. 2 OF 3		
	1.0 OVER	10 UNDER	±---	KTAKAHASHI	2013/07/30			
10 OVER	30 UNDER	±---	APPROVED BY	DATE	SEE CHART			
30 OVER		±---	YNOGAWA	2013/11/07	MATERIAL NO.			
ANGULAR	±---	°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



16	17.5	2.8	8.4	52745-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(B)	(A)	ENG. NO.	極数 CIRCUIT

REVISED EC NO: J2016-0389 DRWN: TMORISHITA 2015/10/20 CHKD: KTAKAHASHI 2015/10/20 APPR: YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER UNDER ±0.03		MM ONLY	---	METRIC	
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY DATE	TITLE		
	0.5 OVER 1.0 UNDER ±0.1		CHECKED BY DATE	0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (3/3)		
	1.0 OVER 10 UNDER ±---		APPROVED BY DATE			
30 OVER 30 UNDER ±---		MATERIAL NO.	DOCUMENT NO.		SHEET NO.	
ANGULAR ±--- °		SEE CHART		SD-52745-057		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				